Advanced Electronics Assembly Conference

Tuesday, 19 November - Budapest, Hungary
Thursday, 21 November - Oradea, Romania

TIME	
8:00	**REGISTRATION OPENS**
9:15-9:30	**Opening Remarks**
	Session 1
9:30-10:15	**CONFERENCE KEYNOTE: From Cardboard to Space - The Raspberry Pi Story** Pete Lomas, FREng., Co-Founder/Hardware Designer, Raspberry Pi
10:15-10:45	**IPC Conformal Coating Material & Application "State of the Industry" Assessment Project** Jason Keeping, P.Eng., Celestica, Inc.
10:45-11:00	**REFRESHMENT BREAK**
	Session 2
11:00-11:30	**Cleanliness Before Conformal Coating** Michael Kövi, ZESTRON Europe
11:30-12:00	**Implementation of a Low Melting Point Soldering Alloy in Electronics Assembly** Gheorghita Chirculete, Ph.D., Comet Electronics
12:00-12:30	**Automotive Grade Solder Paste - How to Engineer the Flux Chemistry to Achieve High SIR and Maximize the Print & Reflow Process Windows** Graham Wilson, Indium Corporation
12:30-13:30	**LUNCH BREAK**
	Session 3
13:30-14:00	**Selective Solder Fine Pitch Components on High Thermal Mass Assembly** Gerjan Diepstraten, Vitronics Soltec BV
14:00-14:30	**Laser Depanelling - The Future?** Allen Duck, Getech Automation
15:30-15:00	**Yield Improvement at NPI Using X-Ray** Keith Bryant, Keith Bryant Consultancy
15:00-15:15	**REFRESHMENT BREAK**
	Session 4
15:15-15:45	**Rework of Hybrid Land Grid-Array Sockets on Large High-Density Printed Circuit Boards** Prabjit Singh, Ph.D., IBM Corporation; Nandu Ranadive, Jabil Inc.
15:45-16:15	**Using JTAG/Boundary-Scan in Maufacturing** Peter van den Eijnden, MSc, JTAG Technologies B.V.
16:15-16:45	**Innovation in Jetting Technology for Advanced Manufacturing** Twan Aldenzee, Mycronic
16:45-17:00	**Closing Comments**
17:00	**Conference Concludes**